RM case study

Case name	Sensor packa	ging		
Dimensions	L = ca. 9 mm	8 8		
in mm (L x	B = ca. 3 mm			
W x H)	H = ca. 2 mm			
(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	(without flex)			
Application	Application Temperature measurement		Section is with 1919-90 Commissionly to the Printed County of the Technology: 3D-CSP with RIMPD - special sensor adaptation with flow interferences	
RM process	3D-CSP, RMPD®		Connected PCB flex circuit sensor interconnection	
Software	SolidWorks/			
	Orcad/Simulation software			
System	3D-CSP, RMPD [®] system			
Material	FDA USP Class VI		3D-CSP System capacitor Signal processor (bare die)	
	biocompatible material		On chip remperatur sensor, resolution 0.1°C "Dvo vide serbi interface (°Cs compatible)	
Lead time	3 weeks from EDA design			
(hours/days)				
Costs	Typically 1 – 10 €	@ 1000)	
	pcs and larger qty.,			
	invest/NRE			
Surface	$R_a < 1 \mu m$		'	
finish	μ μ.			
Mechanical	Soft or hard materials as needed for sensor packaging applications, Conductive lines			
properties	made from Cu, NiCr, Au			
Thermal	Up to 180°C long term			
properties				
Any	3D-CSP package integrating, e.g., sensors, ASICs, discretes.			
additional	Interface to Flex, wire, wireless (3D-CSP antenna coil), connection plug board			
info	available	,		
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Pressure sensor packaging SAW			SAW sensor package with fluidic interconnection	
	face to slot connecto uidic interface	r with		